

# JOM Call for papers

An official publication of The Minerals, Metals & Materials Society

Publication Date: *December 2018*

Manuscript Deadline: *July 1, 2018*

**The Electronic Packaging and Interconnection Materials Committee is seeking papers on the topic of**  
***Advances in Electronic Interconnection Materials Behavior***

This topic will include papers on Pb-free solder development, advances in the understanding of joint reliability and emerging interconnection materials for harsh environments.

Original research papers should be 3,000-6,000 words with up to 8 figures maximum; review papers should be 6,000-10,000 words with up to 15 figures maximum.

Detailed author instructions are available at:

<http://www.tms.org/AuthorTools/>

**Keywords for this topic:**

**Electronic materials; intermetallics; lead, zinc, and tin**

**Guest Editor for this *JOM* topic is Chris Gourlay:**

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If you are interested in submitting a paper, upload your manuscript at

<https://www.editorialmanager.com/jomj/>

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

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